

• General Description

The AGM12T05D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

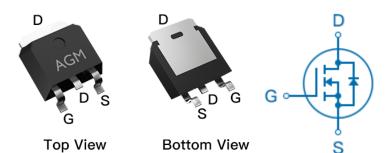
Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
120V	5.3mΩ	100A

TO-252 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM12T05D	AGM12T05D	TO-252	330mm	16mm	2500

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	120	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	100	Α
_	Drain Current-Continuous(T⊂=100℃)	63	Α
IDM (pluse)	Drain Current-Pulsed (Note 2)	400	Α
PD	Maximum Power Dissipation(Tc=25℃)	119	W
	Maximum Power Dissipation(Tc=100℃)	48	W
EAS	Avalanche energy (Note 3)	484	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	${\mathbb C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		50	°C/W
RøJC	Thermal Resistance Junction-Case ¹		1.05	°C/W



Table 3. Electrical Characteristics (TJ=25 ℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	ates			7.		
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	120			V
IDSS	Zero Gate Voltage Drain Current	VDS=120V,VGS=0V			1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2		2.2	V
gFS	Forward Transconductance	VDS=5V,ID=15A		50		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A		5.3	7.0	mΩ
		VGS=4.5V, ID=15A		6.2	8.0	mΩ
Dynamic (Characteristics					
Ciss	Input Capacitance			3614		pF
Coss	Output Capacitance	VDS=40V,VGS=0V ,F=1MHZ		423	-	pF
Crss	Reverse Transfer Capacitance			12		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		0.8		Ω
Switching	Times					
td(on)	Turn-on Delay Time			20		nS
tr	Turn-on Rise Time	VGS=10V,VDS=60V,		65		nS
td(off)	Turn-Off Delay Time	ID=20A,RGEN=5Ω		32		nS
tf	Turn-Off Fall Time			49	1	nS
Qg	Total Gate Charge			60		nC
Qgs	Gate-Source Charge	VGS=60V, VDS=10V, ID=20A		19		nC
Qgd	Gate-Drain Charge	15 2011		15		nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)				100	А
VSD	Forward on Voltage	VGS=0V,IS=20A			1.2	V
trr	Reverse Recovery Time	IF=20A , dl/dt=100A/μs ,		60	-	ns
Qrr	Reverse Recovery Charge	TJ=25℃		109		nc

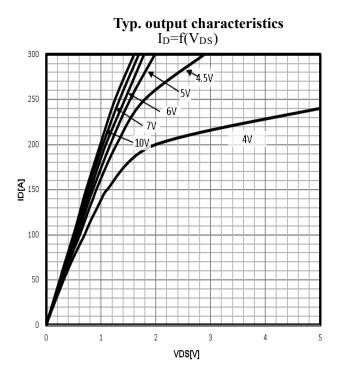
Notes 1. The maximum current rating is package limited.

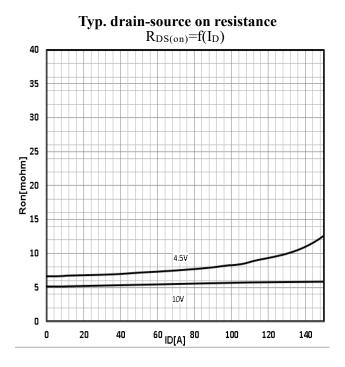
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

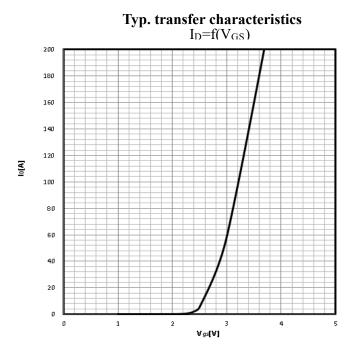
Notes 3.EAS condition: TJ=25 $^{\circ}$ C , VDD=40V,Vgs=10V,ID=44A,L=0.5mH,RG=25ohm

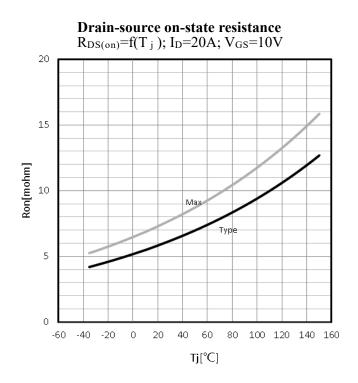


Characteristics Curve:

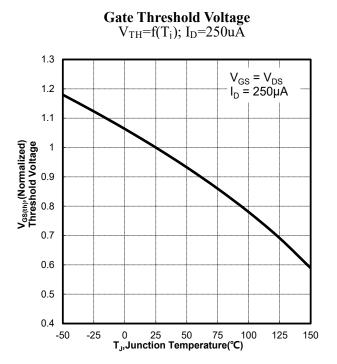


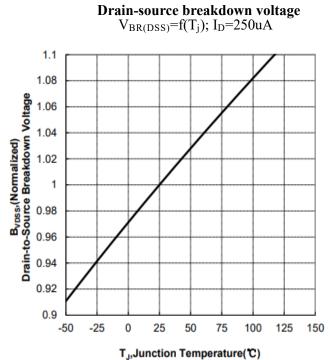


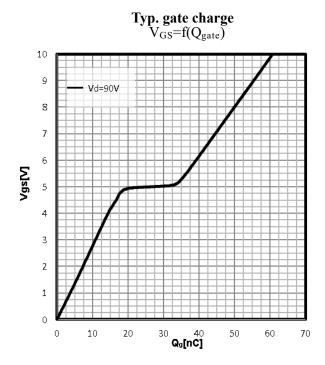


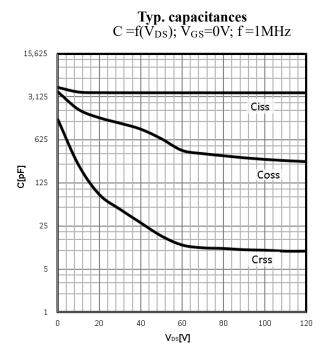




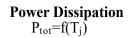


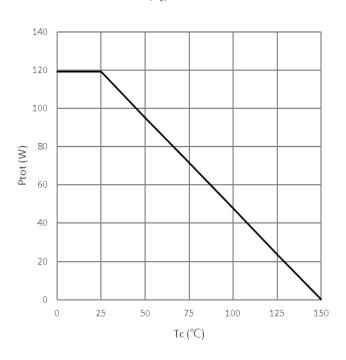


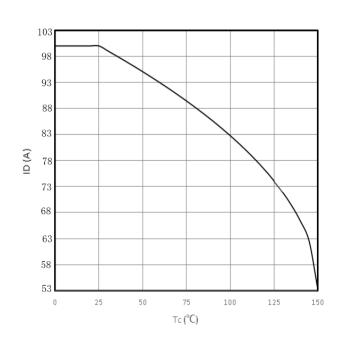




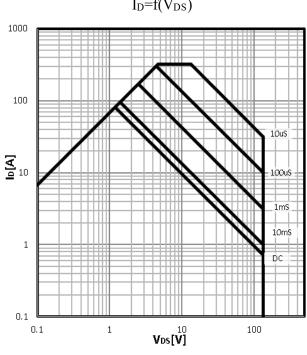




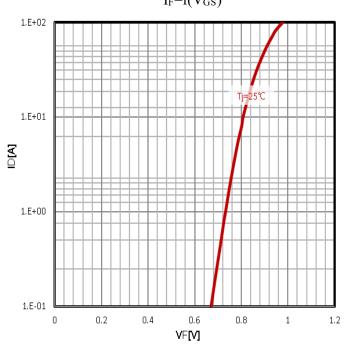




Safe operating area $I_D = f(V_{DS})$



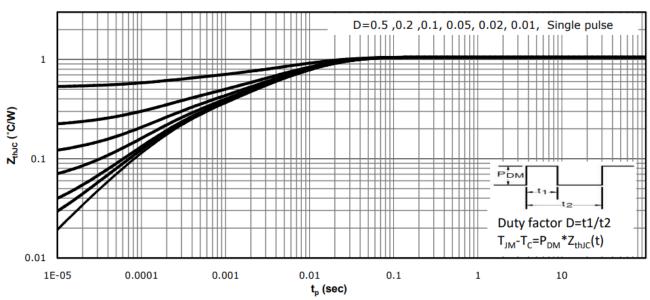
Body Diode Forward Voltage Variation $I_F = f(V_{GS})$





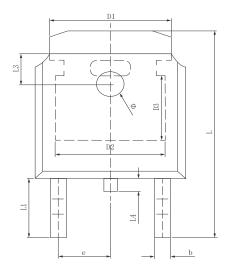
Max. transient thermal impedance

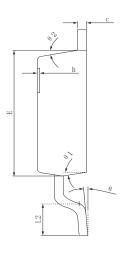


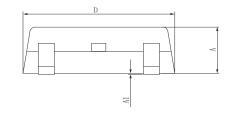




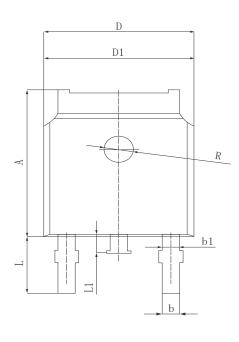
•Dimensions (TO-252)

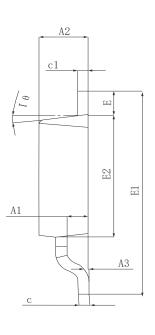


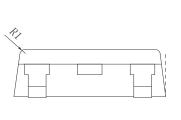


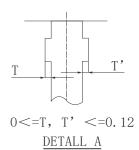


	MILLIMETER		
SYMBOL	MIN	Typ.	MAX
A	2. 200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1		5.334 REF	
D2	4.826 REF		
D3	3.166 REF		
Е	6.000	6.100	6.200
е	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Ф	1.100	1.200	1.300
θ	0°		8°
θ 1	9° TYP		
θ2	9° TYP		

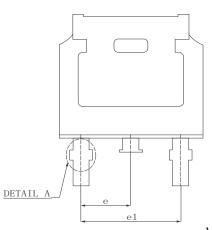






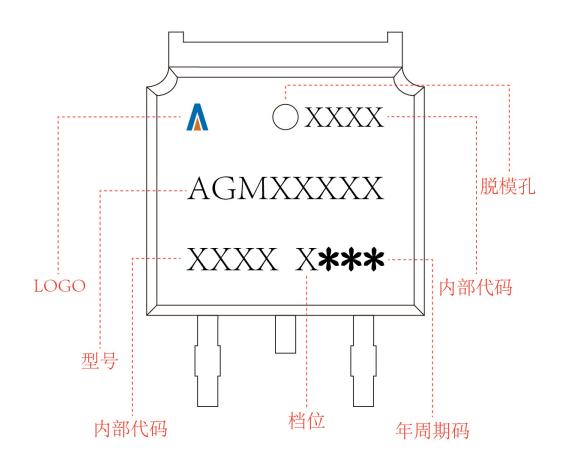


our mor	MILLIMETER		
SYMBOL	MIN	NOM	MAX
A	7.050	7. 100	7. 150
A1	0.960	1.010	1.060
A2	2. 250	2.300	2.350
A3	0.000	0.050	0.100
b	0.760REF.		
b1		1.000REF.	
С	0. 508REF.		
c1	0.508REF.		
D	6. 550	6.600	6.650
D1	5. 220	5. 320	5. 420
Е	0.950	1.000	1.050
E1	9.700	9.900	10.100
E2	6.050	6.100	6.150
е	2. 286BSC		
e1	4. 572REF.		
L	2.650	2.800	2.950
L1	0.700	0.800	0.900
θ 1	7° REF.		
R	1.300REF.		
R1	0. 250REF.		





TO-252 Marking Instructions:





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